



ECC/DSP System Architecture for Enabling Reliability Scaling in Sub-20nm NAND

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Forward-Looking Statements

During our presentation today we may make forward-looking statements.

Any statement that refers to expectations, projections or other characterizations of future events or circumstances is a forward-looking statement, including those relating to market growth, industry trends, future memory technology, technology transitions and future products. This presentation contains information from third parties which reflect their projections as of the date of issuance.

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We undertake no obligation to update these forward-looking statements, which speak only as of the date hereof.

Disclaimer: This tutorial provides an overview of various techniques and concepts, some or all of which may not necessarily reflect what SanDisk is actually using in their products.

- Gap Between Product Requirements and Technology Capability
 - Applications Requirements: Endurance, Performance, Power
 - Reliability Challenges with Scaling
- ECC/DSP solutions
 - Tier 0: Adaptive NAND Parameters Optimization
 - Tier 1: Noise Reduction
 - Tier 2: Advanced Error Correction Coding (ECC)
 - Tier 3: Second level Error Correction (RAID)
 - Tier 4: Flash Management Algorithms
 - Tier 5: Host Data Manipulation
- Summary

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Increasing Product Requirements

Faster
Application
Execution



4

Faster
Web
Browsing



Smoother
Multi-
tasking



Computational
Photography



Longer
Battery
Life, Power
Savings



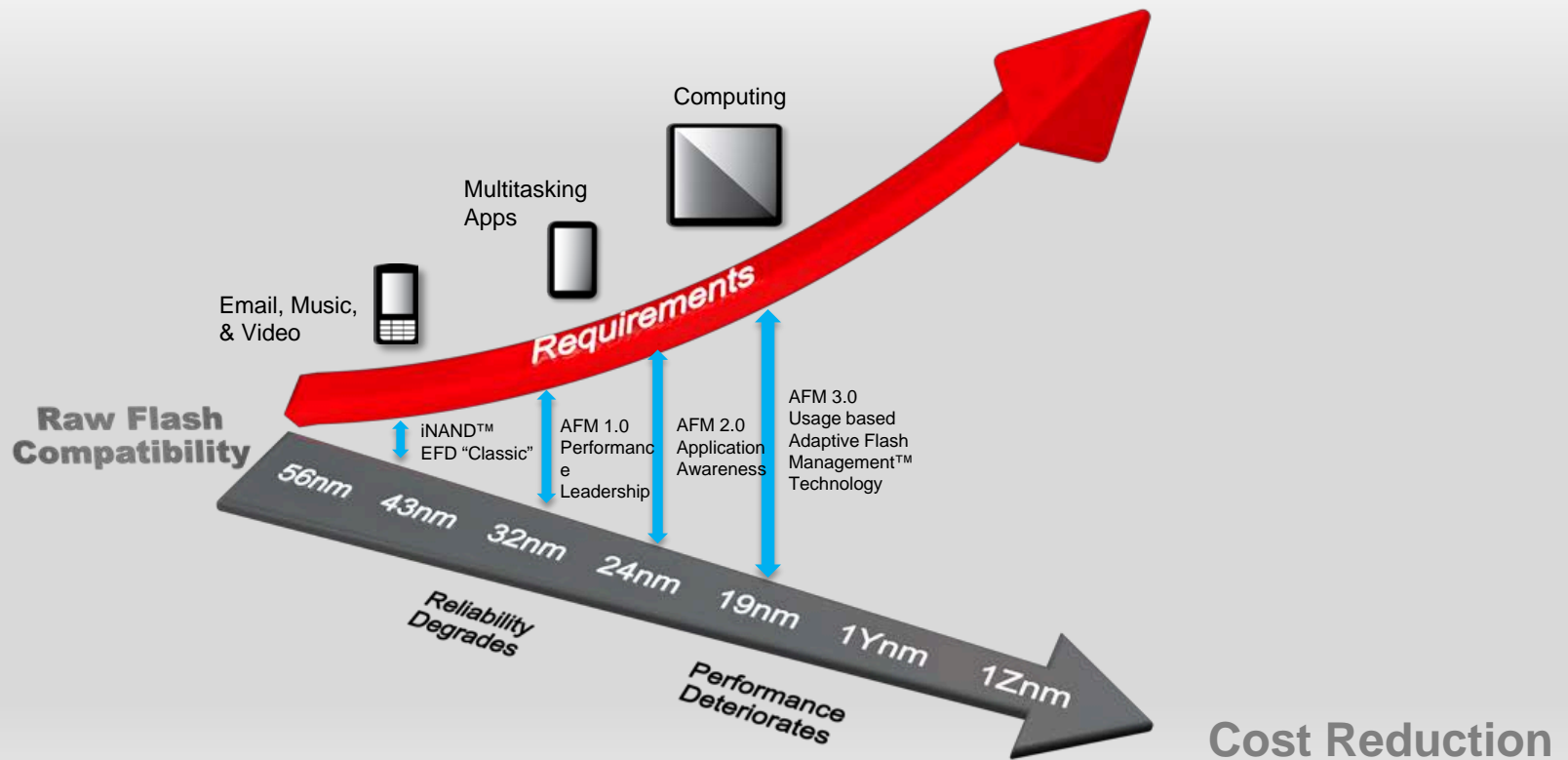
Sharing,
Connectivity



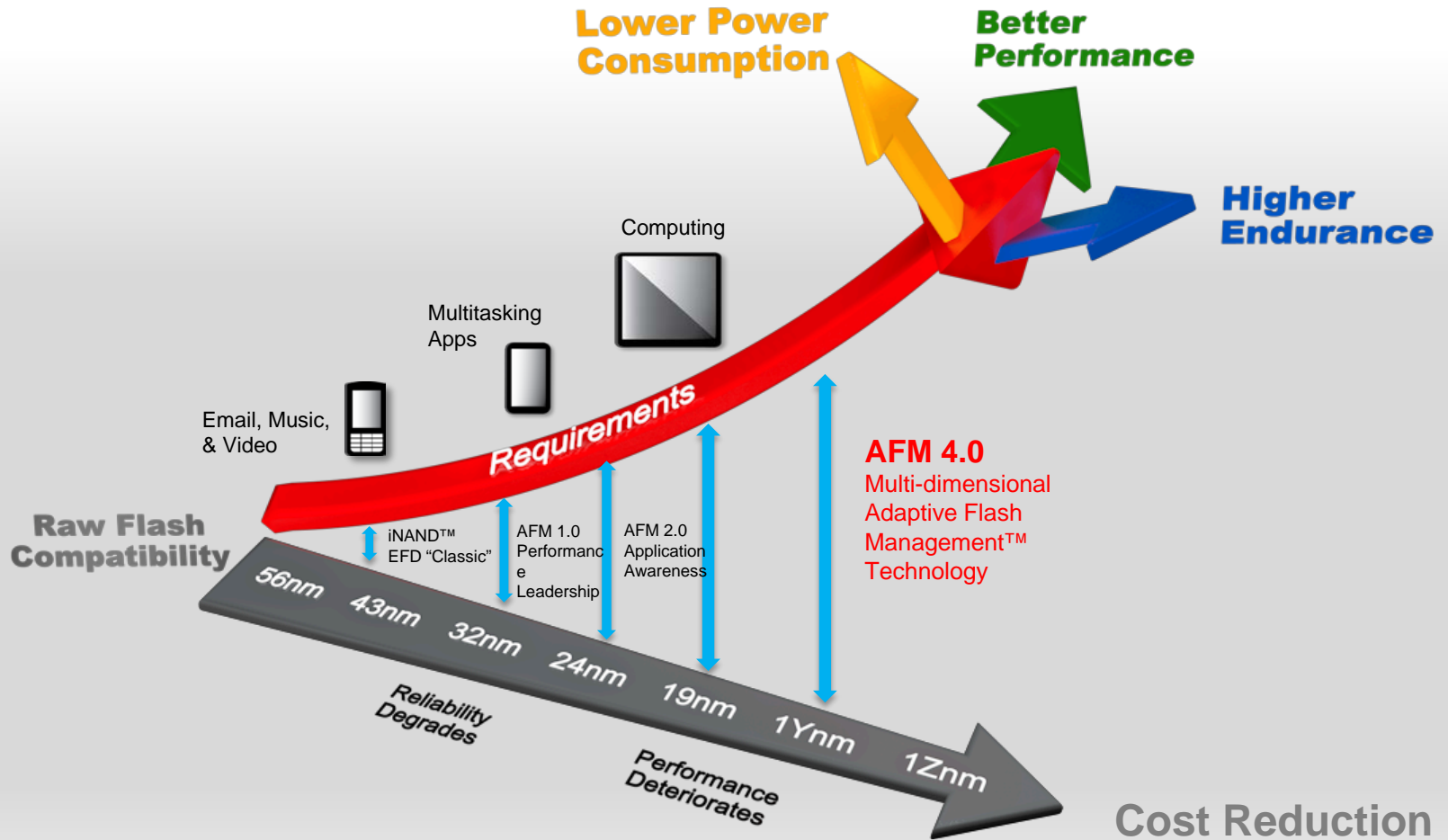
Higher
Resolution
Video



Gap Between Raw Memory Capability and Applications Requirements



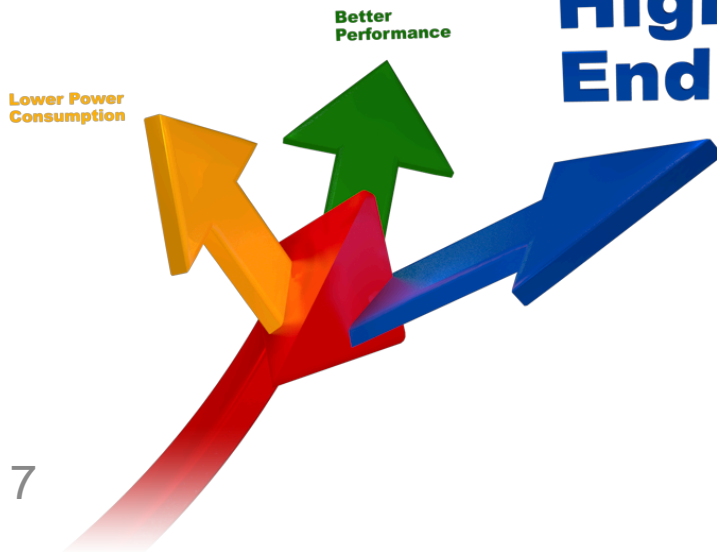
Gap Between Raw Memory Capability and Applications Requirements



Optimized **Endurance**
for enhanced
**video download &
application caching**



**Higher
Endurance**



Optimized **Performance**
for superior
gaming experience

**Better
Performance**



**Lower Power
Consumption**

**Higher
Endurance**

Optimized Power Consumption for longer web browsing

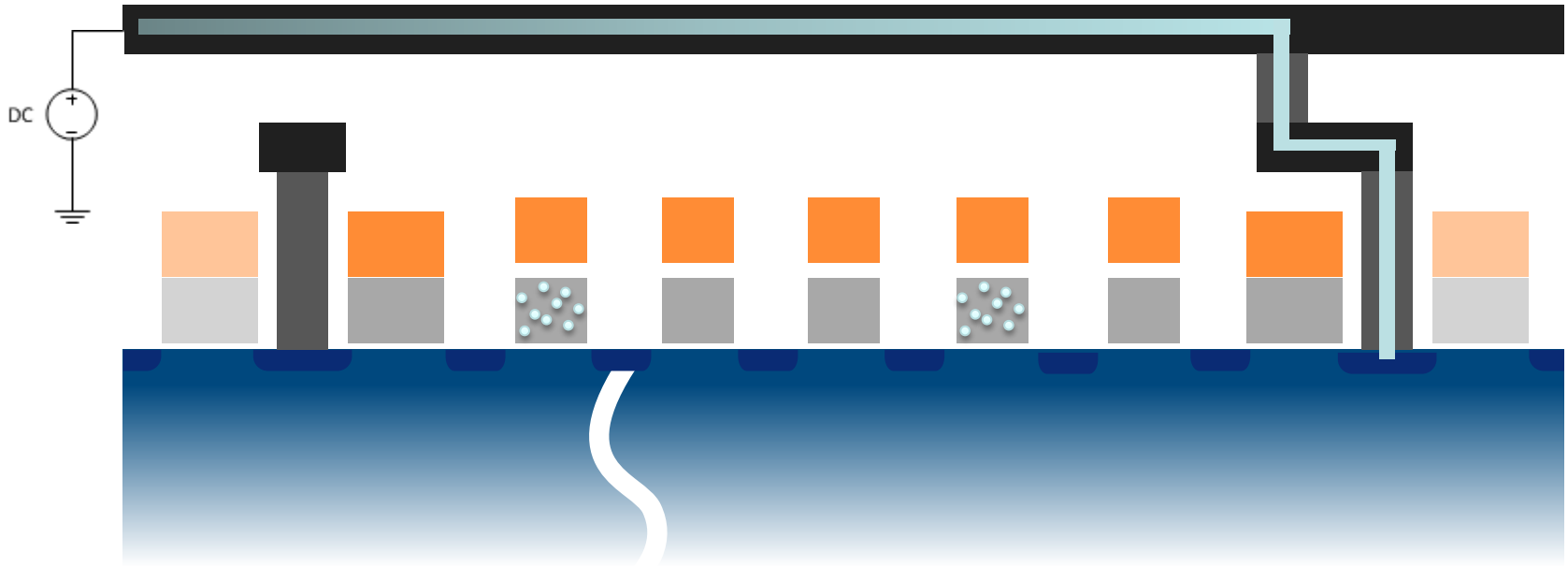
Lower Power Consumption



Reliability Challenges with Scaling

*As an example we will describe the phenomena
of Read Disturb*

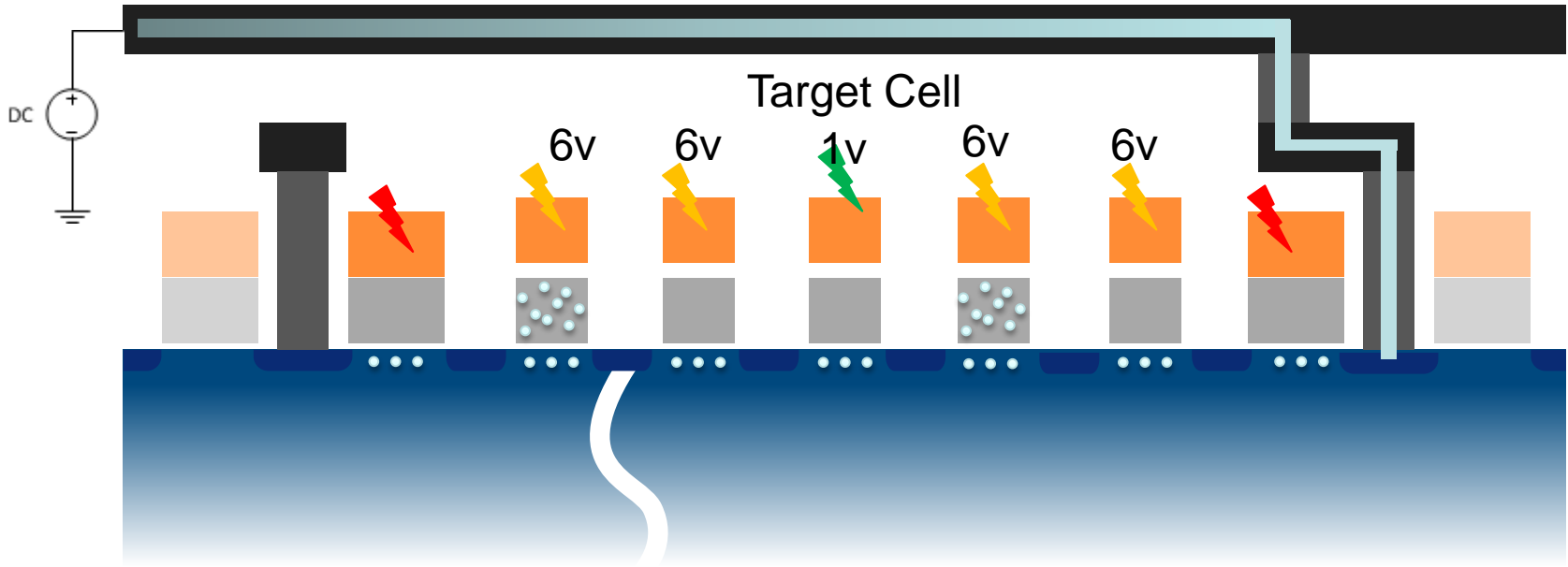
Read Operation



1. BL Pre-Charge

Read Operation

Threshold Voltage numbers are nominal

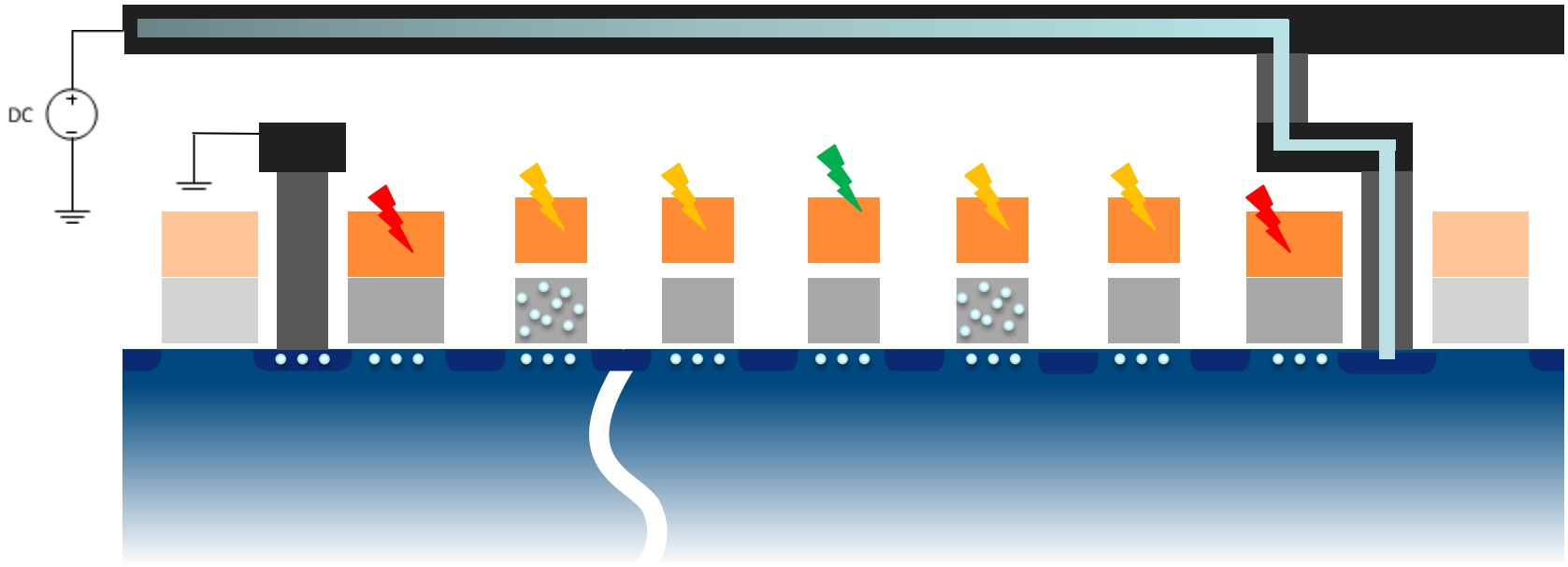


1. BL Pre-Charge
2. Gate Voltages

- Opens “select gate” transistors
- Opens unselected cells – “Victims”
- Senses state of selected cell – “Target”

Read Operation

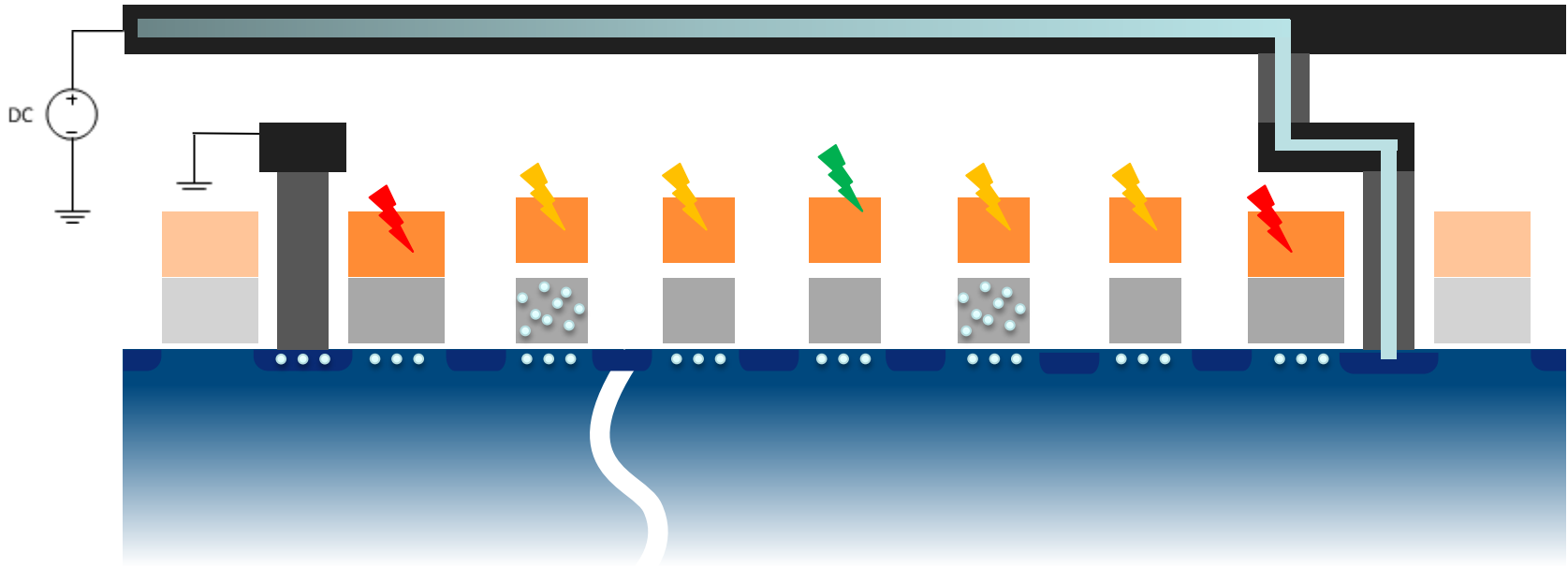
Target Cell is Erased – Read “1”



1. BL Pre-Charge
2. Gate Voltages
3. Sensing

Read Operation

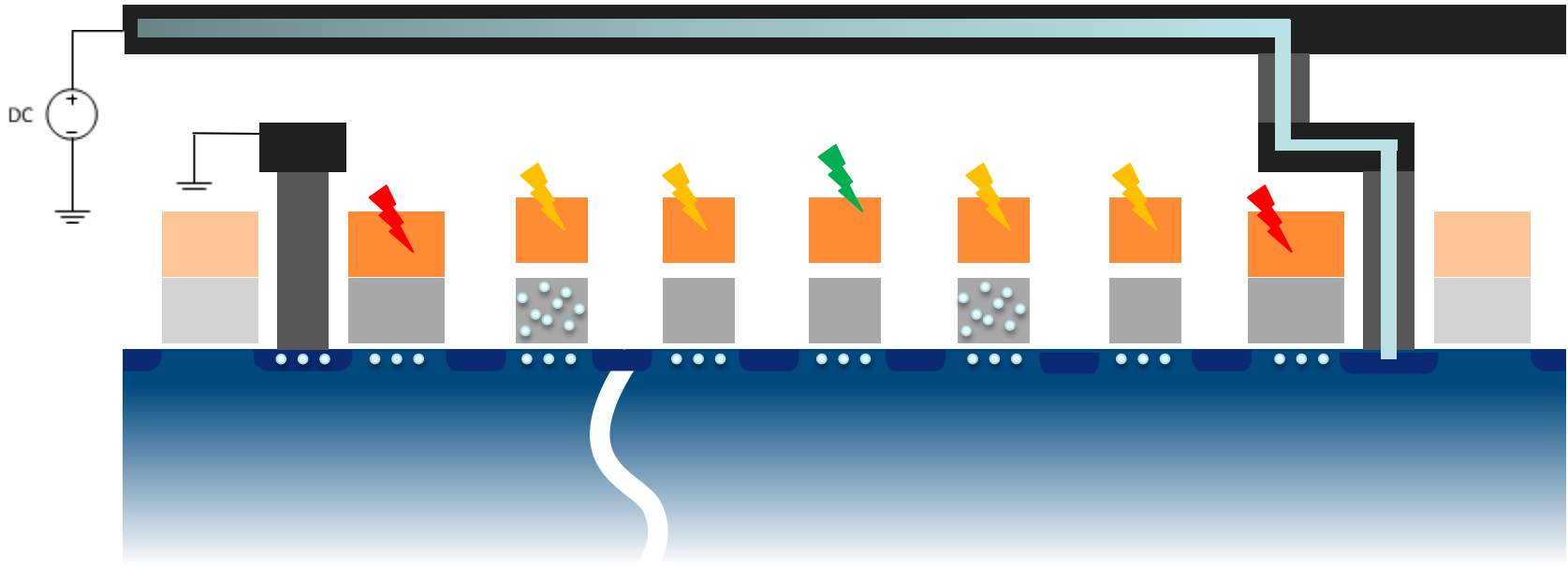
Target Cell is Erased – Read “1”



1. BL Pre-Charge
2. Gate Voltages
3. Sensing

Read Operation

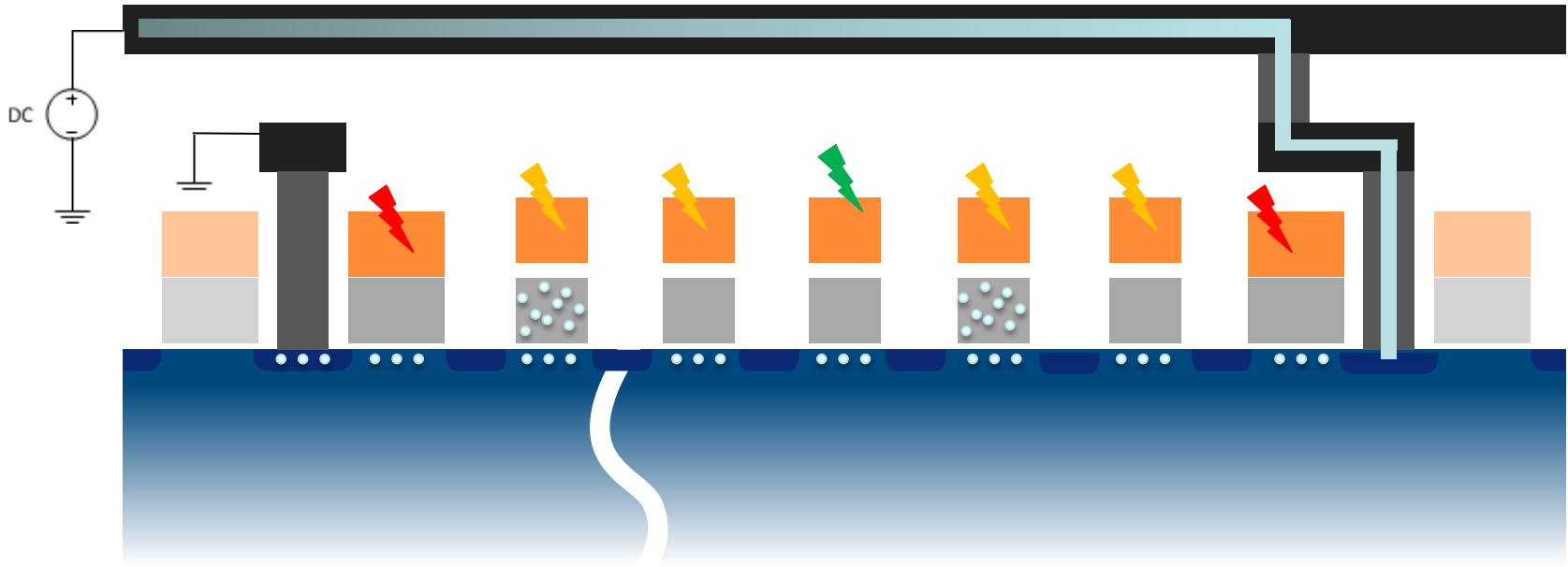
Target Cell is Erased – Read “1”



1. BL Pre-Charge
2. Gate Voltages
3. Sensing

Read Operation

Erased Cell – Read “1”

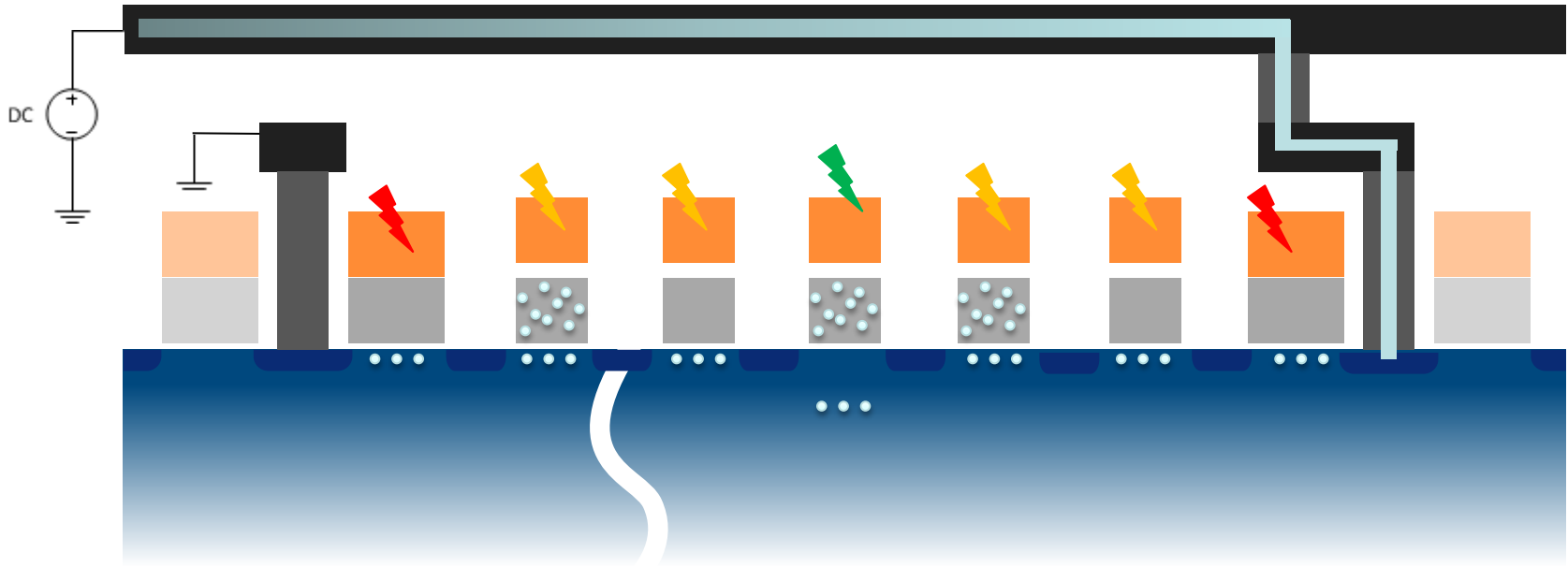


1. BL Pre-Charge
2. Gate Voltages
3. Sensing

Current is Sensed
➤ Cell is Erased!
Read “1”

Read Operation

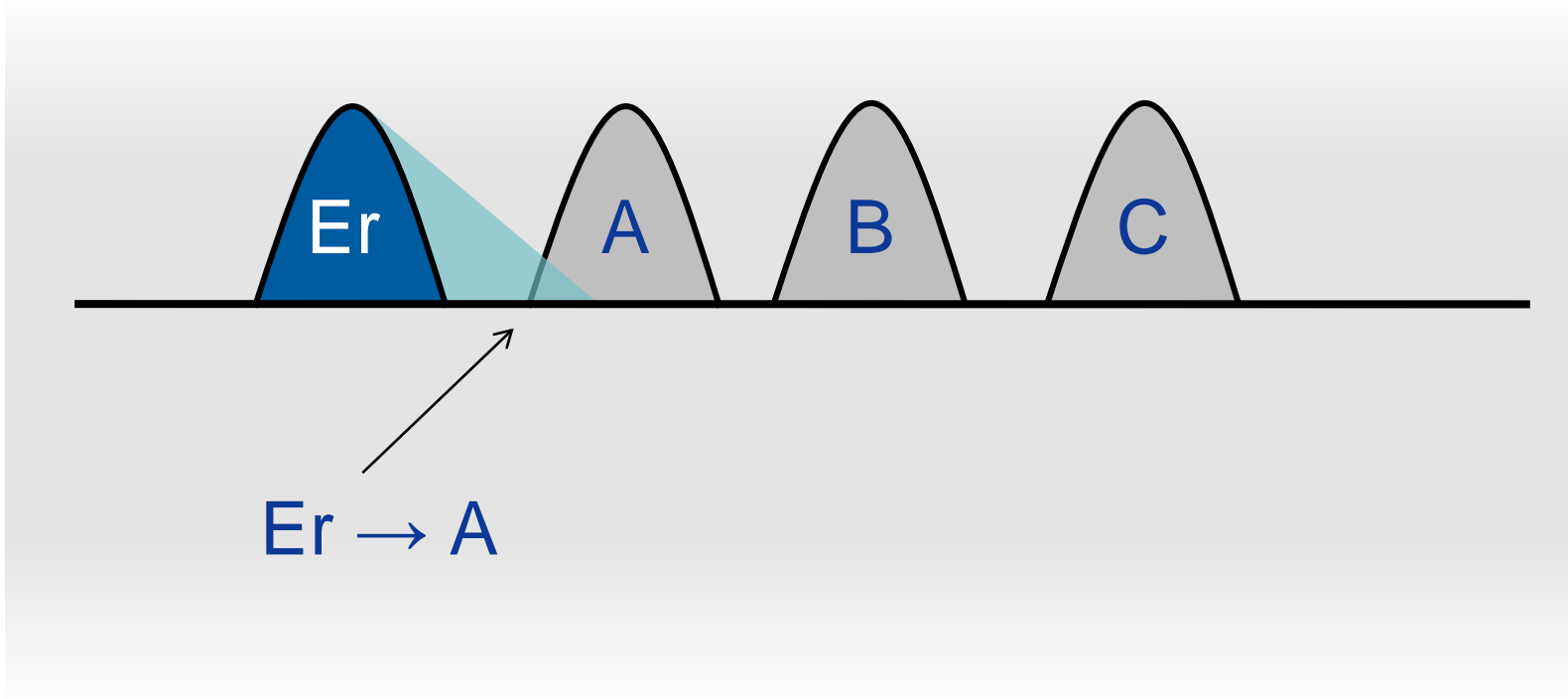
Target cell is Programmed – Read “0”



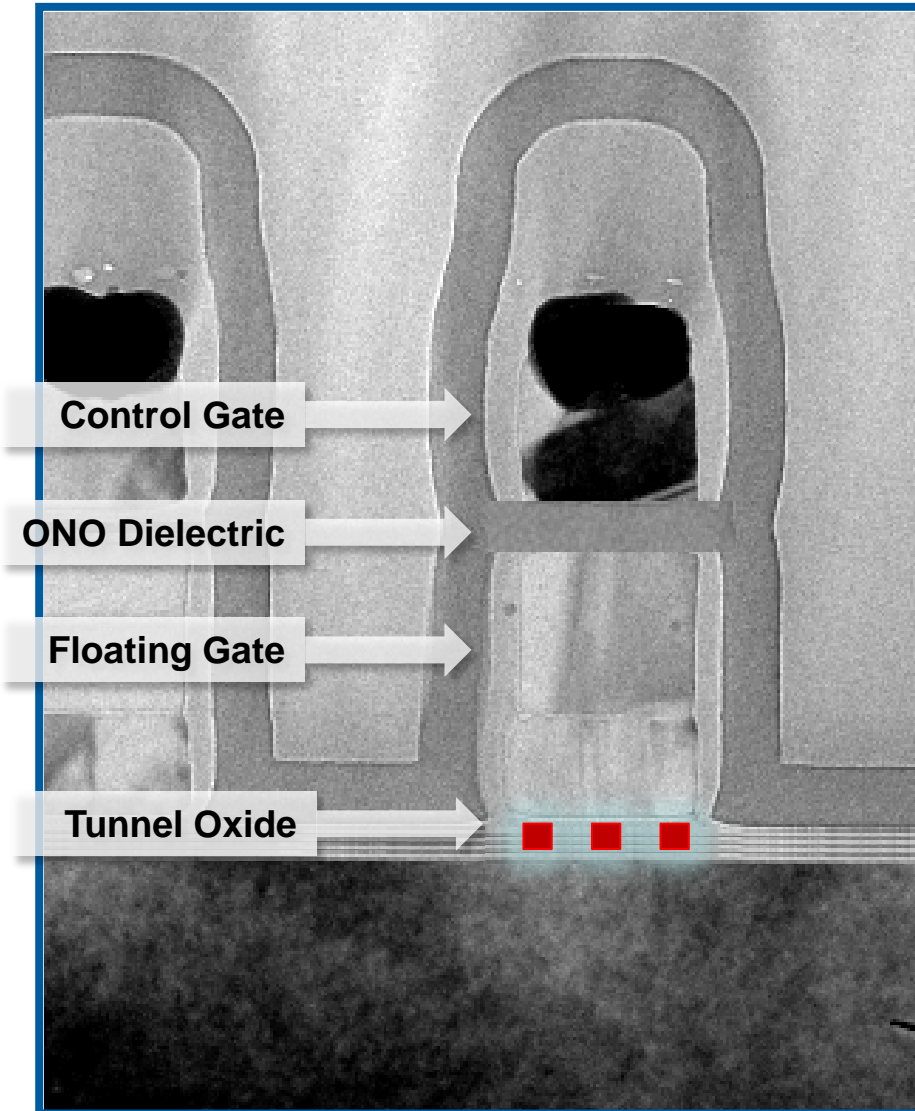
1. BL Pre-Charge
2. Gate Voltages
3. Sensing

Current is NOT Sensed
➤ Cell is Programmed!
Read “0”

Read Disturb

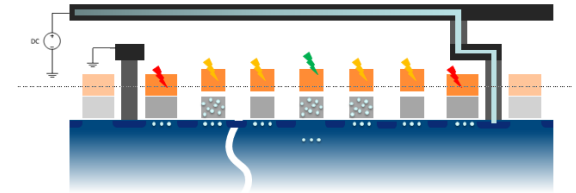


Read Disturb

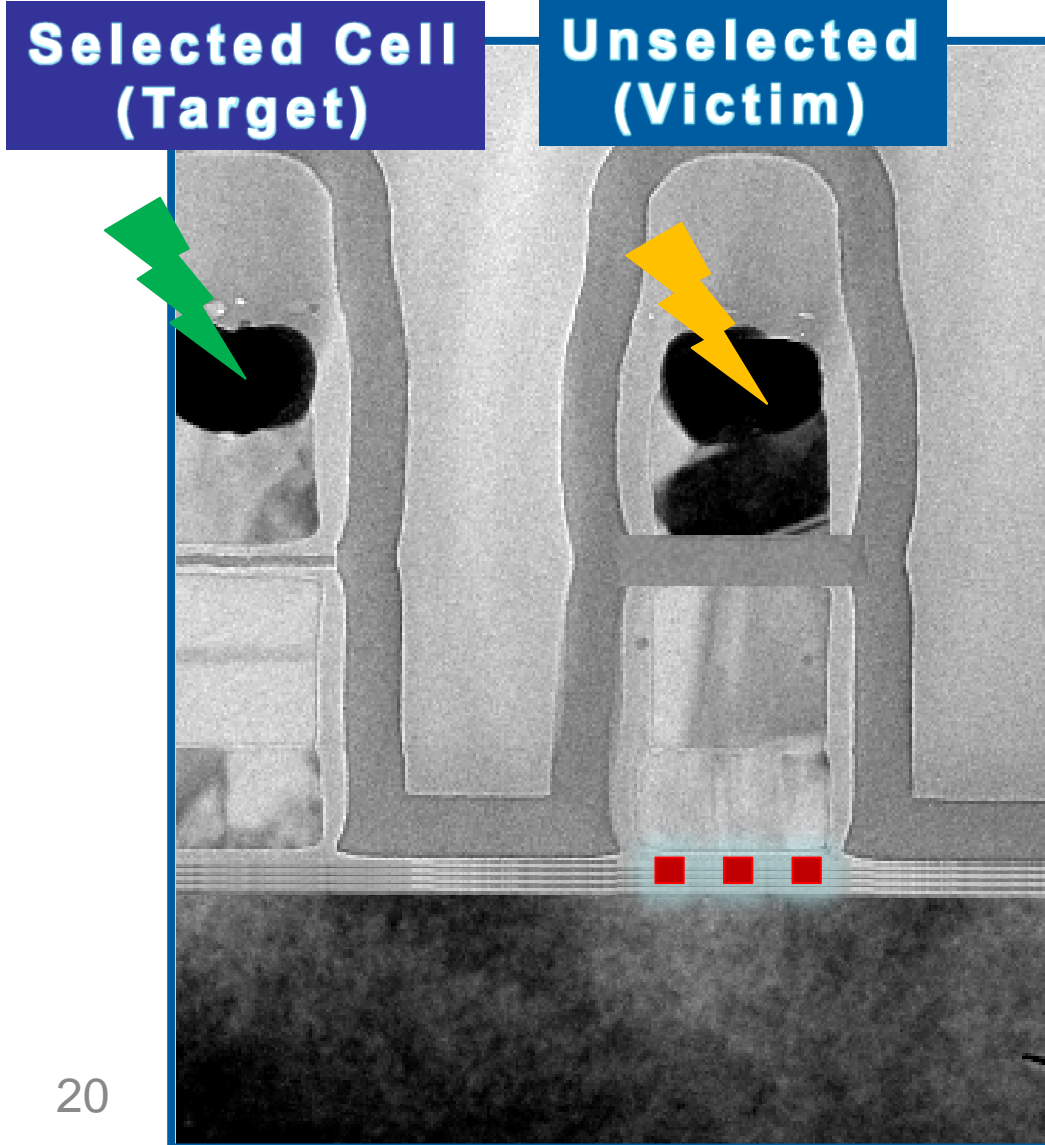


- P/E cycles leads to Tunnel Oxide (Tox) degradation that creates traps

Read Disturb

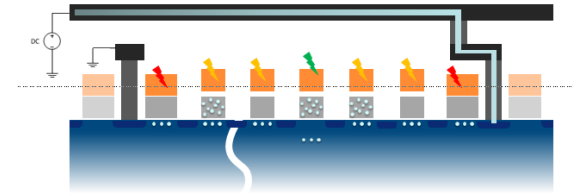


1. BL Pre-Charge
 2. Gate Voltages
 3. Sensing
- Current NOT Sensed
➢ Cell is Programmed!



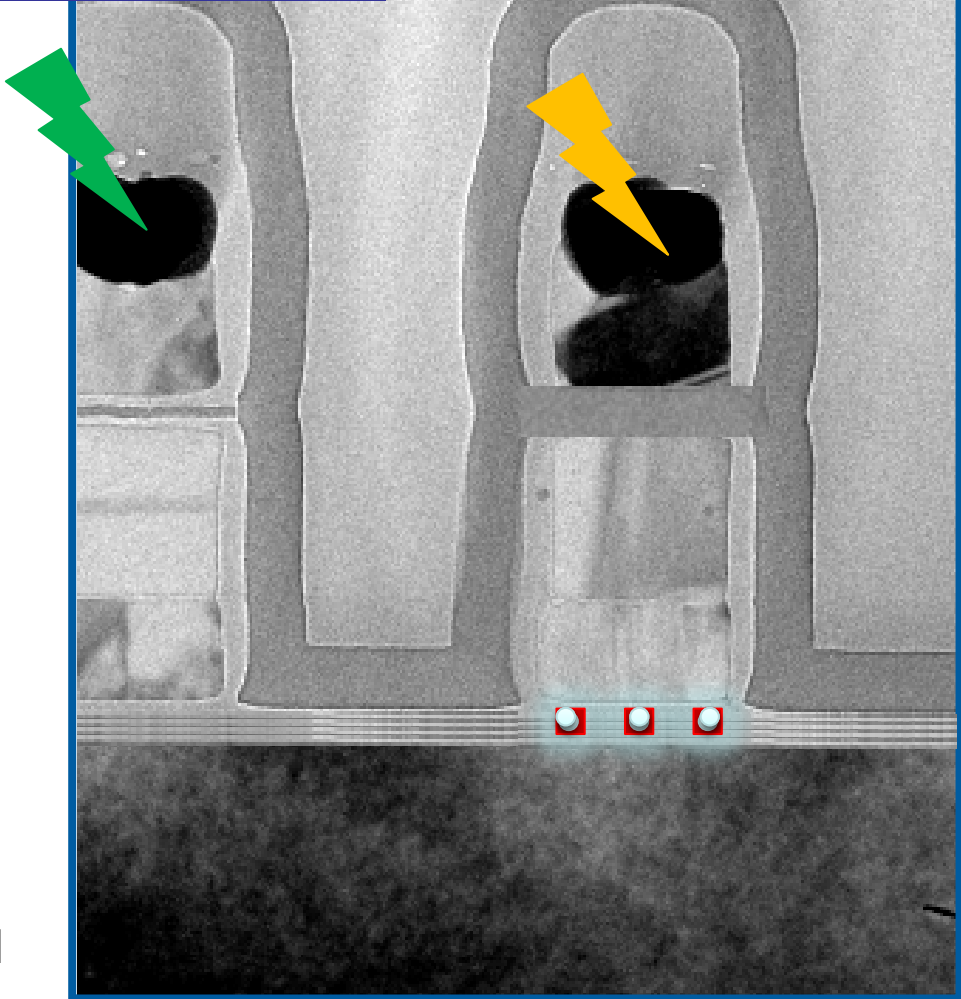
- P/E cycles lead to Tunnel Oxide (Tox) degradation that creates traps
- “Weak Programming” in unselected cells due to unintentional tunneling of electrons to the FG

Read Disturb



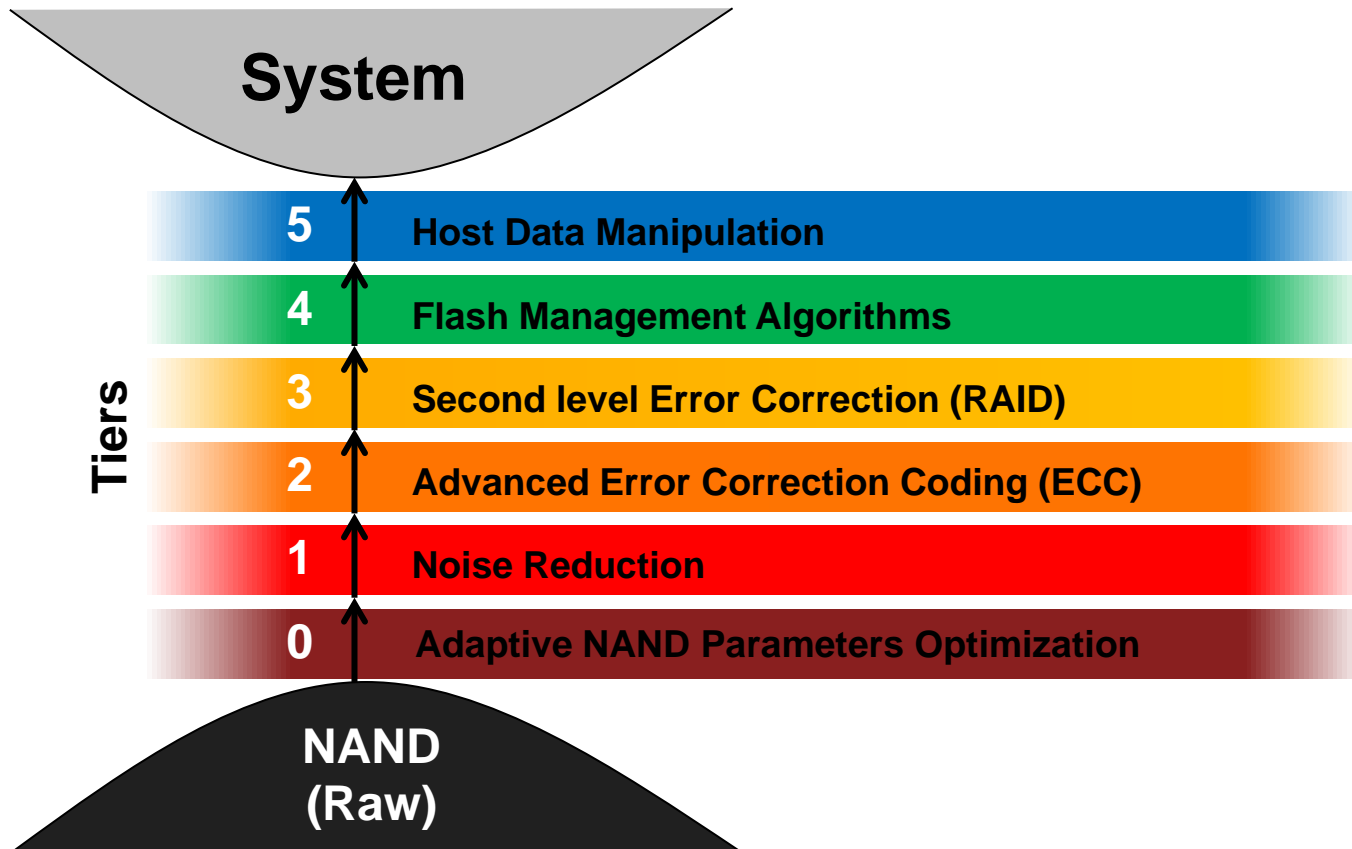
1. BL Pre-Charge
 2. Gate Voltages
 3. Sensing
- Current NOT Sensed
➤ Cell is Programmed!

Selected Cell (Target) **Unselected (Victim)**



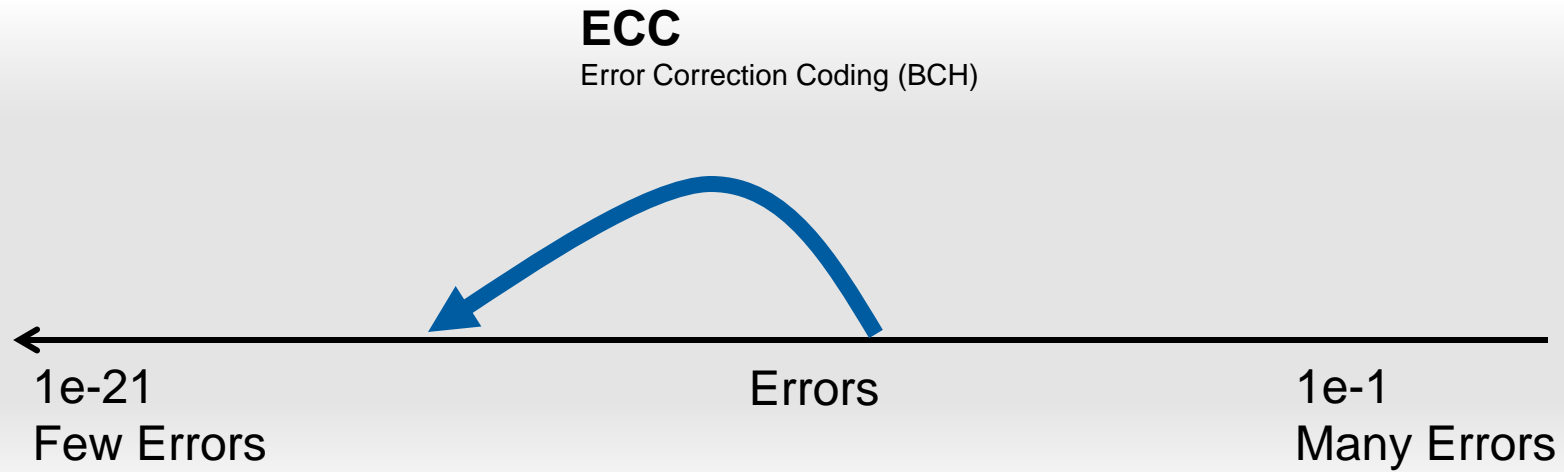
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ECC/DSP Methods: from NAND to System



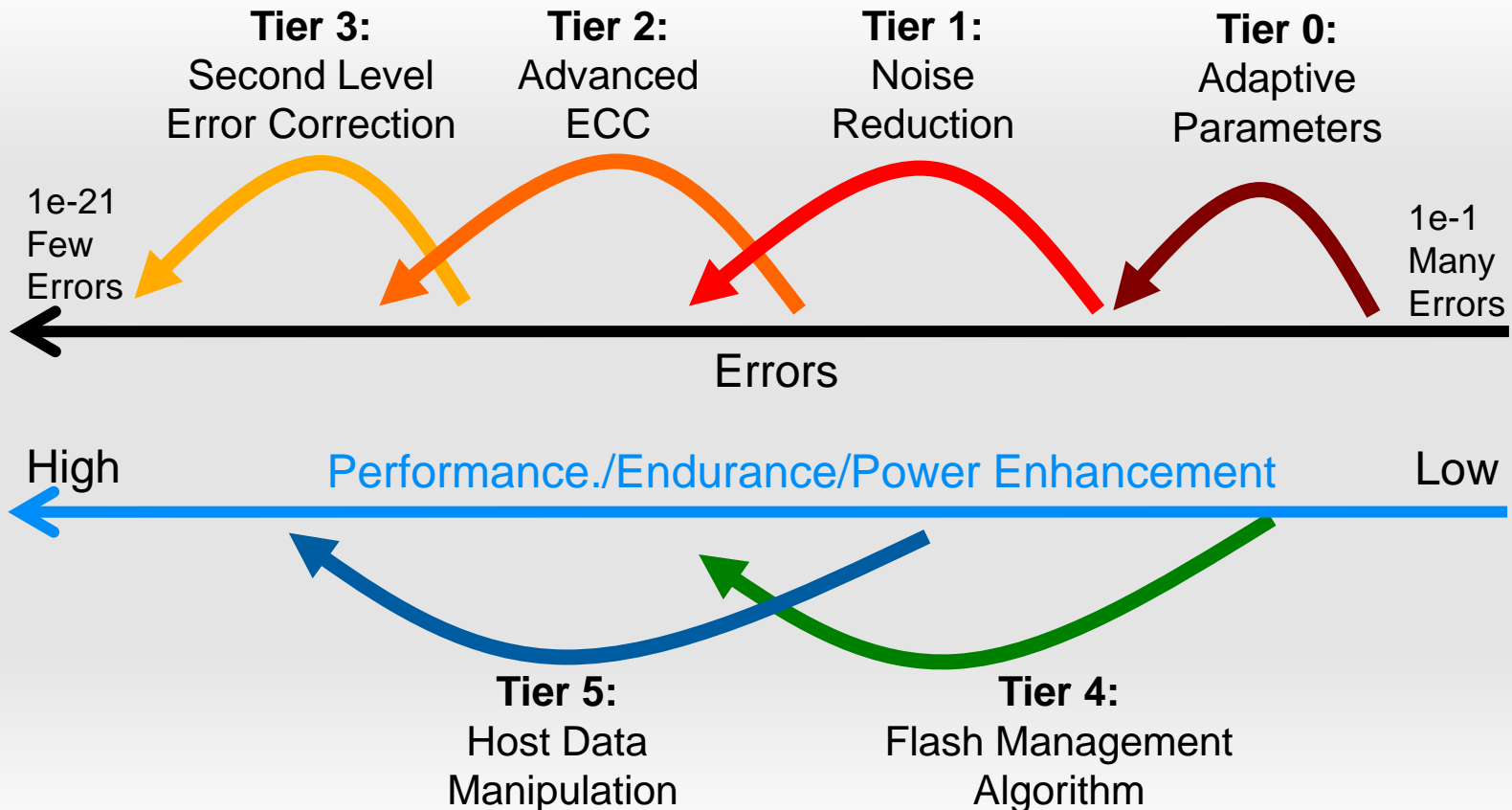
Error Handling System Solutions

Early Technologies



Basic ECC sufficient to meet application requirements

Error Handling System Solutions *Advanced (Sub-20nm)*



Sophisticated ECC and DSP techniques applied to mitigate the natural drift in reliability, and to meet the more demanding requirements of embedded application.

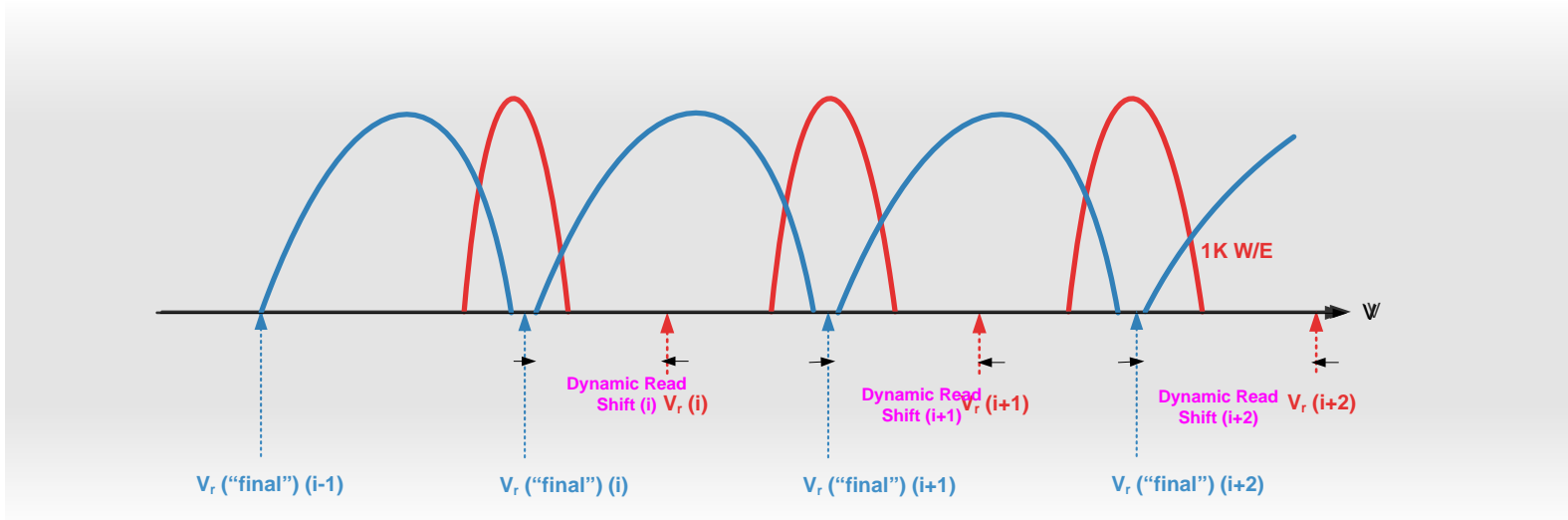
Tier 0: Adaptive NAND Parameters Optimization

- Adaptive NAND parameters optimization along the memory lifetime.
- Parameter setting (“trimming”) of the Program, Erase and Read parameters.
- System level feedback adapts the parameters to:
 - Memory wearing and error rates along the lifetime
 - Die to die, block to block, WL to WL variations within the memory
 - Host data patterns
- Once NAND level optimization has been exhausted, the residual noises and errors need to be handled at system level

Adaptive Read Thresholds – Example

Problem:

- Cell Voltage Distribution is not fixed:
 - Changes along the memory lifetime with W/E cycling and time (DR)
 - Variations within a die - changes from Block to Block, WL to WL,...
- Using a fixed set default thresholds result in high BER and decoding failure



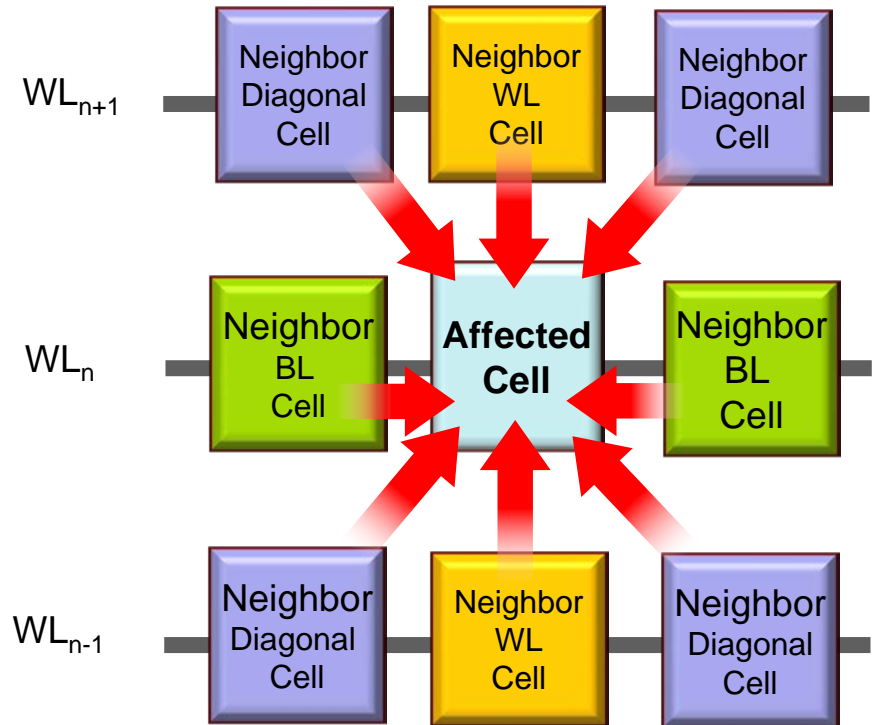
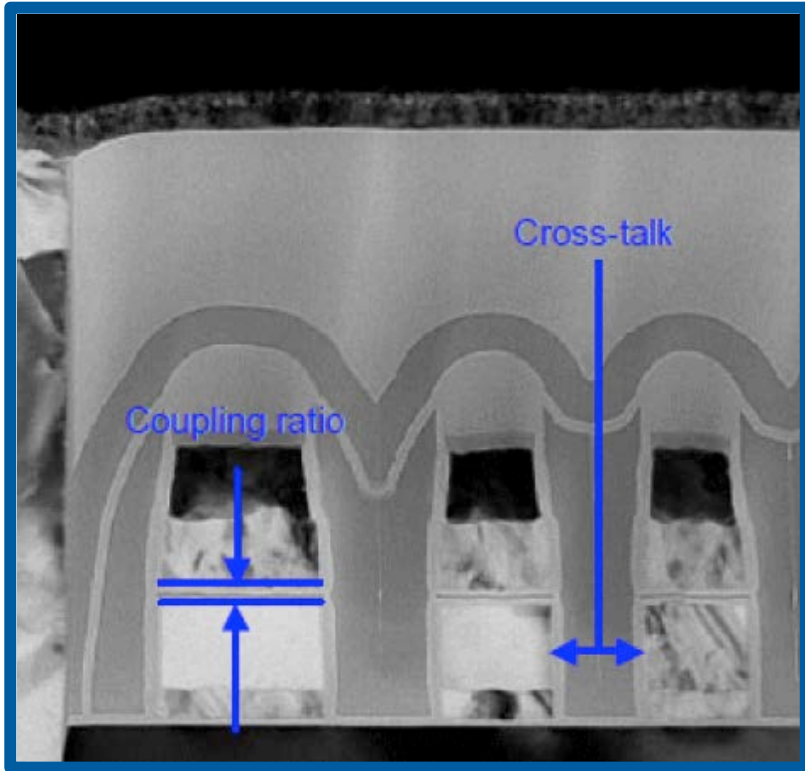
Solution:

- Adaptive read thresholds

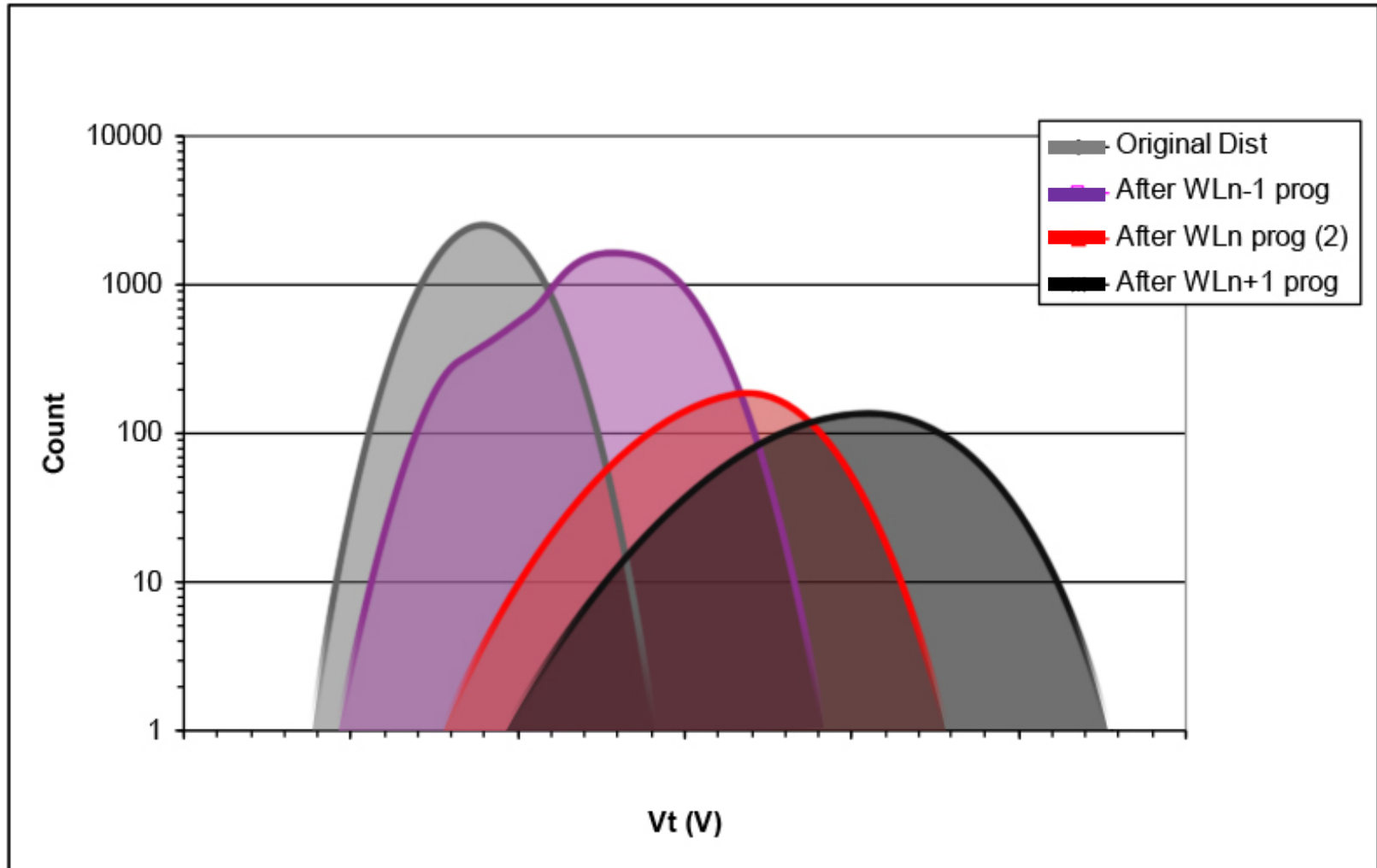
Tier 1: Noise Reduction

- System level residual NAND “noise” reduction via DSP and coding techniques, aimed at reducing error rates to a bare minimum level
 - Tier 1 countermeasures may reduce raw NAND error rates from a $\sim 1E-1$ error level to $\sim 1E-2$ error level
 - Tier 1 countermeasures are aimed at:
 - Ensuring that the next Tier 2 Error Correction Coding (ECC) is cost effective (i.e. less redundancy)
 - Maximizing performance and reducing power consumption
 - Tier 1 countermeasures deal with non intrinsic “noises”, which can be cancelled out, mitigated or compensated for:
 - Data dependent noises such as cross-coupling induced widening, back pattern effects, Program and Read Disturbs, Over programming errors, etc.

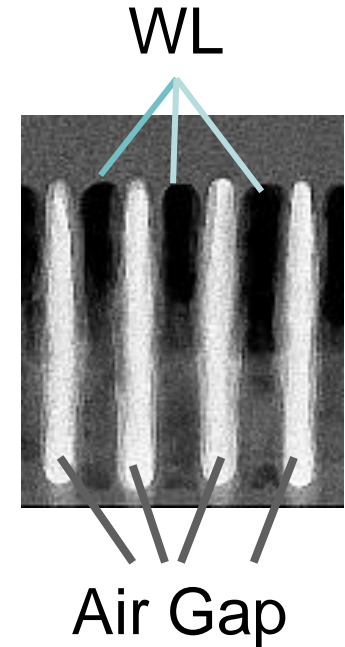
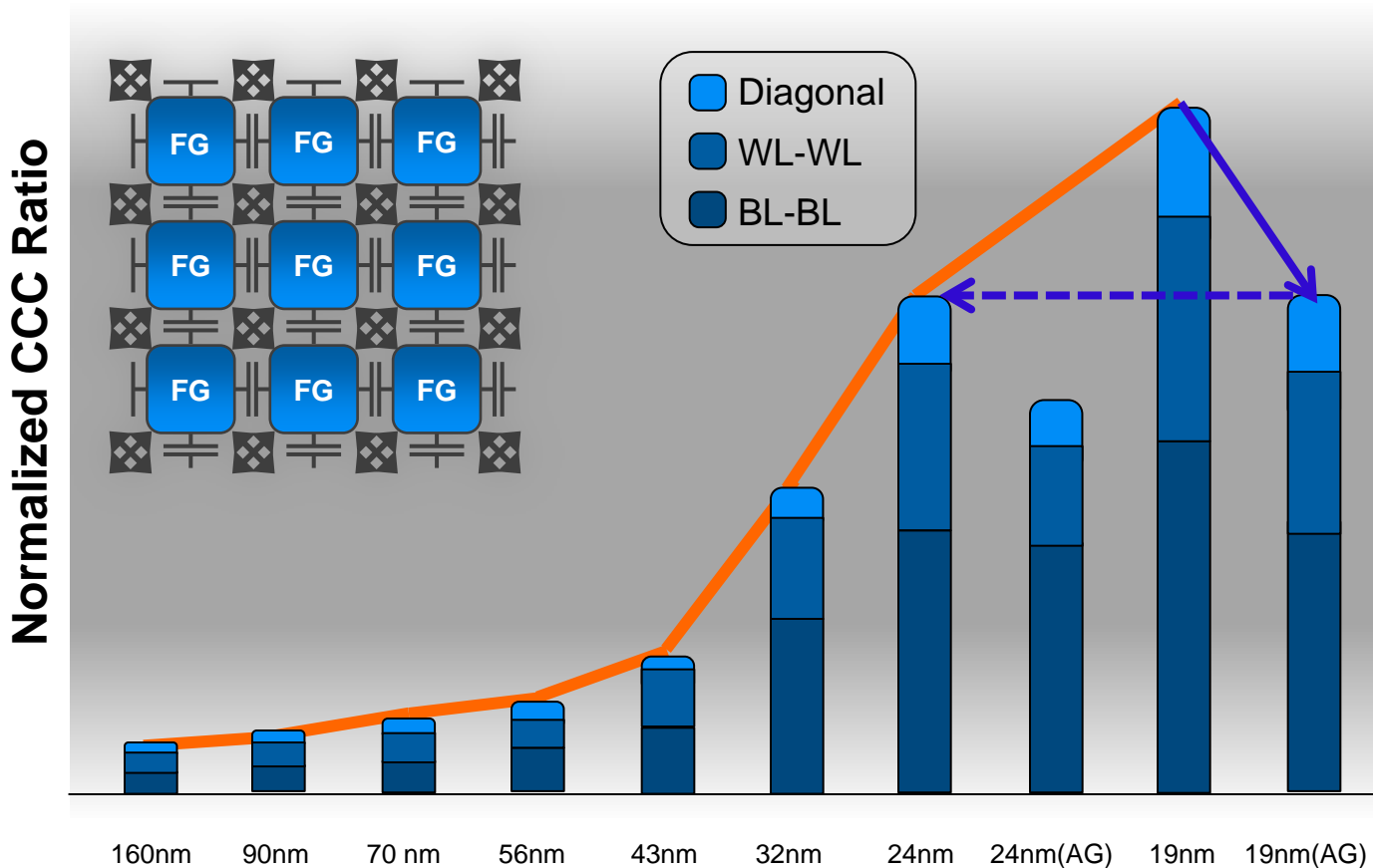
NAND Scaling Challenges – Interferences



Cross Coupling Widening effect



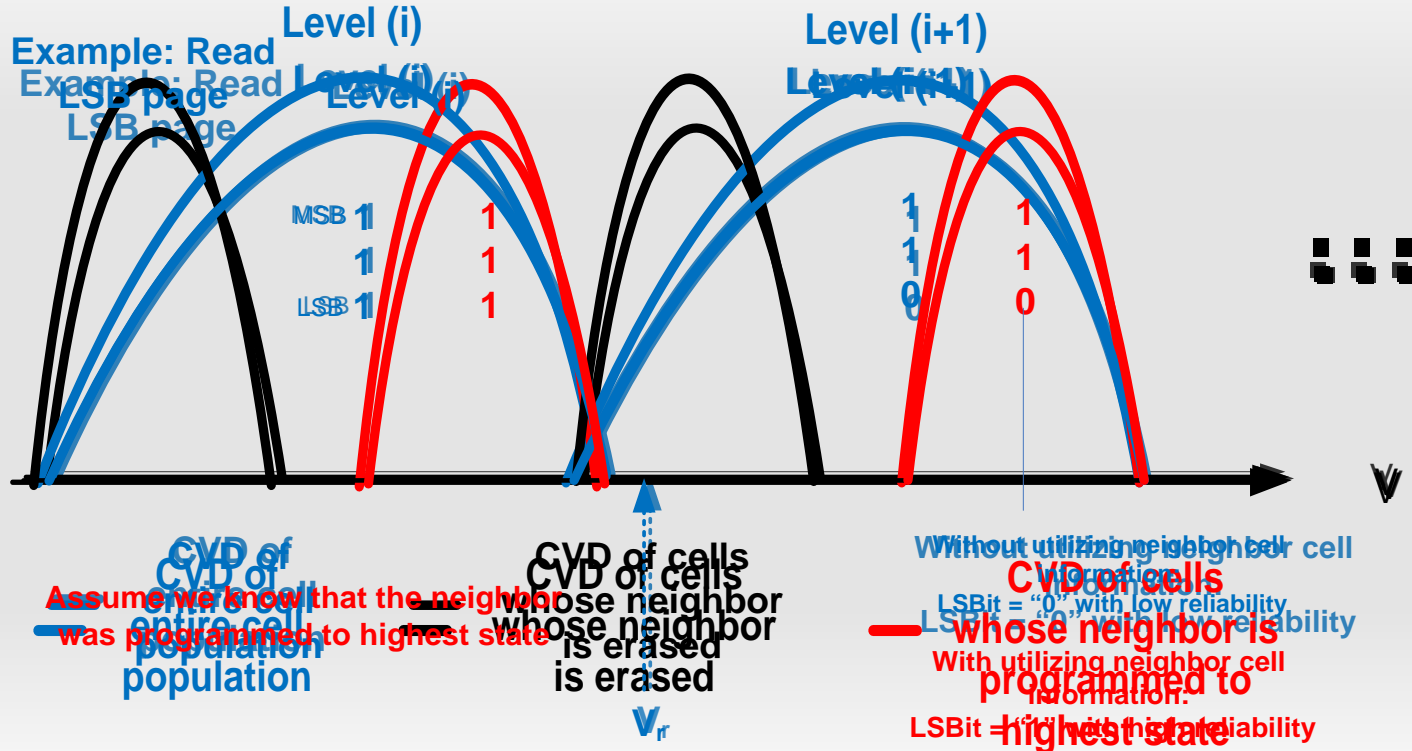
Cell-to-Cell Coupling (CCC) Trend



- With technology scaling, CCC increases dramatically
- Air Gap technology make the 19nm (AG) CCC equivalent to 24nm (no AG)~ 27% reduction

Mitigating Data Dependent Noises

Digitally mitigating cross coupling and other data depended noises during read by taking into account the neighboring cell's read state



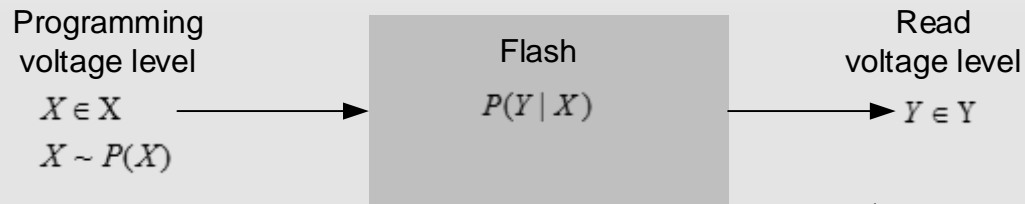
Tier 2: Advanced Error Correction Coding (ECC)

- Advanced Error Correction Coding (ECC) is required in order to handle the residual errors of tier 1
 - Tier 2 ECC can reduce the $\sim 1E-2$ residual error levels of tier 1 to $\sim 1E-16$ error level
 - State of the art iterative coding techniques, such as LDPC, are replacing algebraic coding techniques, such as BCH codes
 - Advanced ECC techniques are essential for achieving an optimal cost, endurance and performance tradeoff, as they allow operation near the theoretic limits (Shannon limit), providing maximal correction capability for a given amount of overprovisioning (“ECC redundancy”)

Flash Information Theory...

How can we compute the Flash capacity?: *Information Theory* (Shannon 1948)

Based on knowing probability to read a voltage level Y given that a voltage level X was programmed



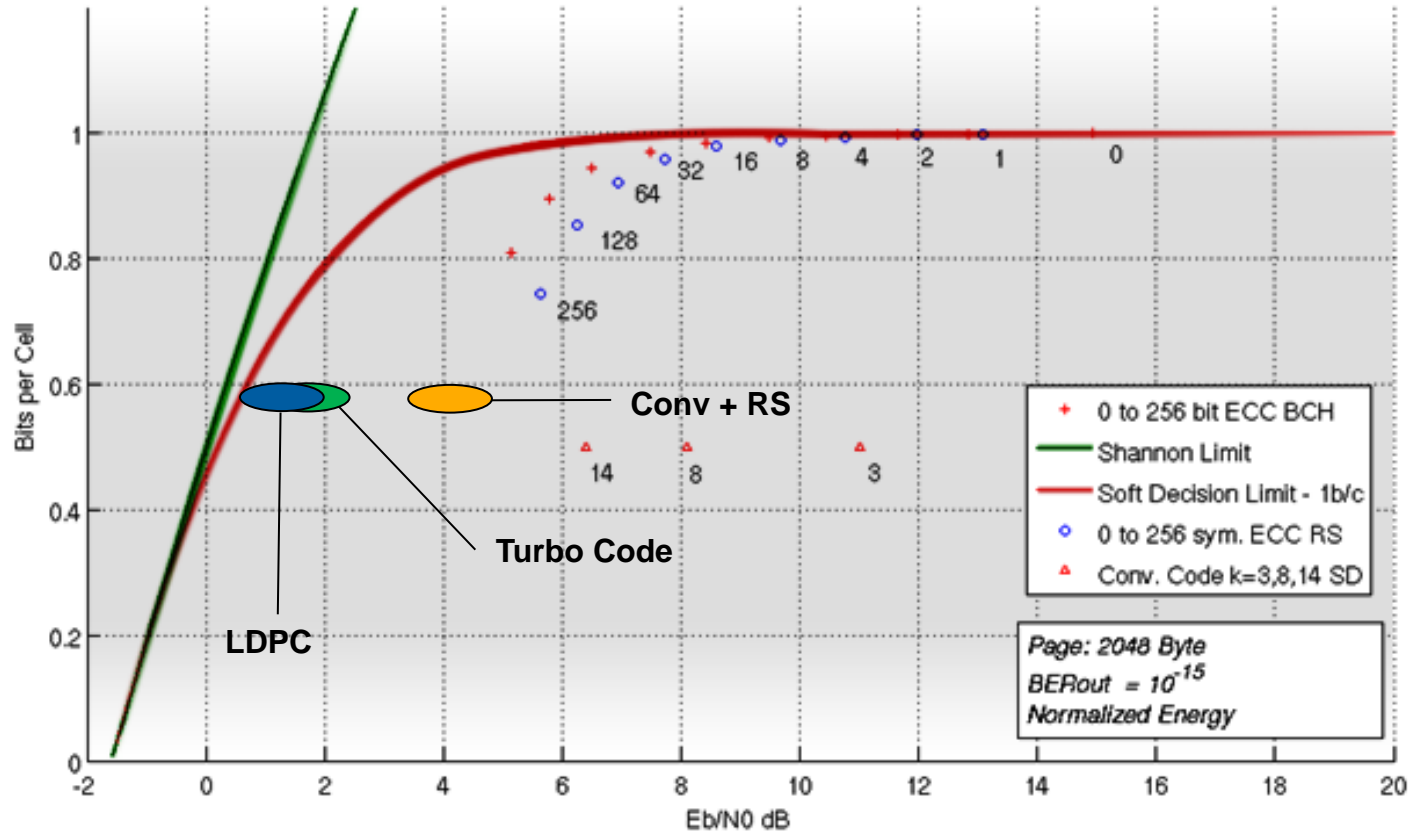
For such a simplified model:

$$C = \max_{P(X)} I(X; Y) = \max_{P(X)} \sum_{X, Y} P(X) P(Y | X) \log_2 \left(\frac{P(Y | X)}{\sum_X P(X) P(Y | X)} \right) \frac{\text{information bits}}{\text{cell}}$$

Actual computations are more complicated. Depend on:

- Verify and read voltage levels
- Data retention
- P/E cycles
- Temperature
- Tuning voltage ambiguity
- Cross coupling
- Back pattern
- Program/Read disturb
- ...

Approaching the Shannon Limit

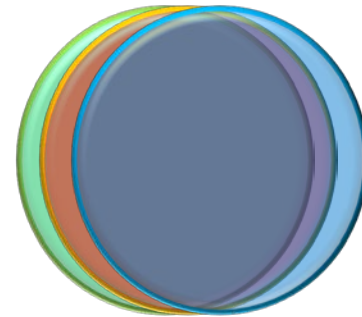
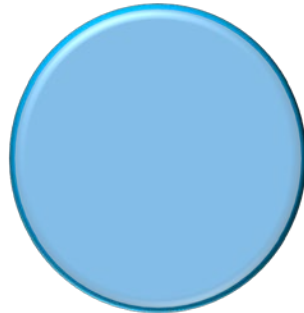
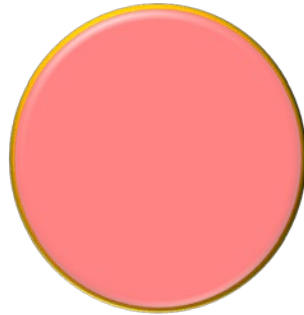


Source: Forward Insights

Tier 3: Second level Error Correction (RAID)

- For enhanced reliability, especially required for SSD applications, a second level error correction, aimed to deal with complete NAND failures resulting in colossal errors, is required. RAID like techniques are used for that purpose.
 - Tier 3 level protection is used for both:
 - Reducing tier 2 error rates from $\sim 1E-16$ to $\sim 1E-24$ or lower
 - Reducing dPPM levels due to gross NAND failure, such as WL breaks, WL shorts, etc.
 - Tier 3 protection may require extra overprovisioning, or may only maintain the overprovisioning temporarily in the controller until verifying data integrity.

RAID Example



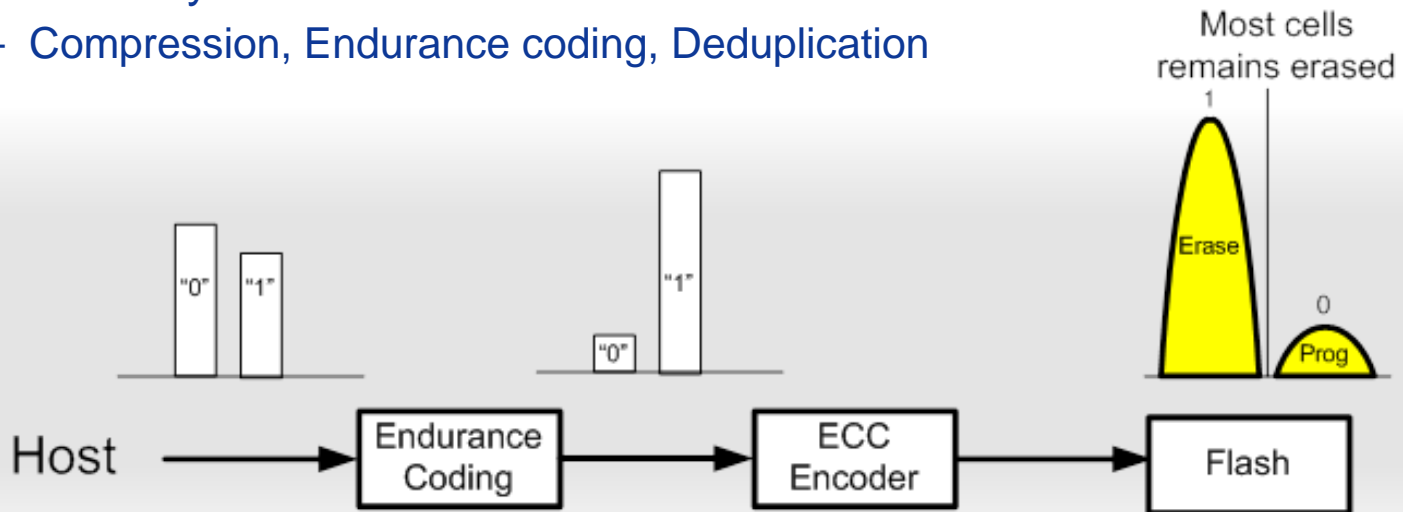


Tier 4: Flash Management Algorithms

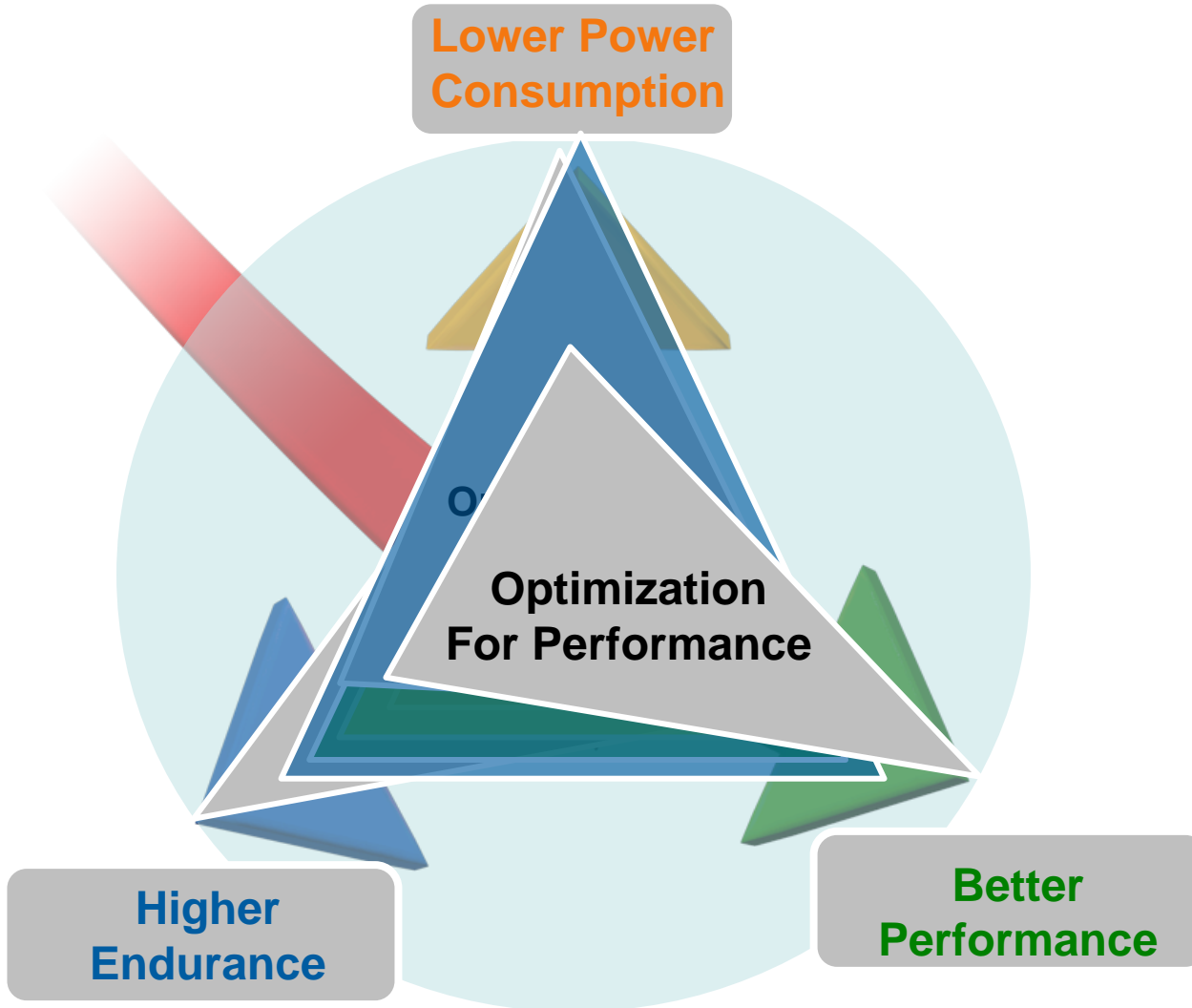
- Back End Flash Management algorithms which manage how logical data is stored on the physical NAND level, in a way that will provide the best performance (both sequential, random or any other combined use case) and the best endurance
- Examples of Flash management functions are:
 - Logical to physical address
 - Wear leveling
 - Garbage collection

Tier 5: Host Data Manipulation

- Host data manipulation, leveraging the inherent “redundancy” in the host data for improving endurance, performance and power
 - Examination of host data produced by users or arising from various operating and file system shows that a significant fraction of the data is of low entropy, having many repetitive data patterns
 - Low entropy data from the host can be manipulated by the controller in various ways:
 - Compression, Endurance coding, Deduplication



Summary



Tier 0:
Adaptive Parameters

Tier 1:
Noise Reduction

Tier 2:
Advanced ECC

Tier 3:
Second Level Error Correction

Tier 4:
Flash Management Algorithm

Tier 5:
Host Data Manipulation

Optimization:
Optimization for different tradeoffs



Thank you!